1 Features

- Reference voltage tolerance at 25°C
  - 0.5% (B Grade)
  - 1% (A Grade)
- Minimum typical output voltage: 2.5 V
- Adjustable output voltage: \( V_{\text{ref}} \) to 36 V
- Operation from \(-40^\circ\text{C}\) to \(+125^\circ\text{C}\) (Q temp)
- Maximum temperature drift
  - 17 mV (I Temp)
  - 27 mV (Q Temp)
- 0.3-Ω Typical output impedance
- Sink-current capability
  - \( I_{\text{min}} = 0.08 \text{ mA (max)} \)
  - \( I_{KA} = 15 \text{ mA (max)} \)
- Reference input current \( I_{\text{REF}} \): 0.4 \( \mu \text{A (max)} \)
- Deviation of reference input current over temperature, \( I_{\text{I(dev)}} \): 0.3 \( \mu \text{A (max)} \)
- Packages: 1-mm x 1-mm X2SON or SOT23-3

2 Applications

- Adjustable voltage and current referencing
- Secondary side regulation in Flyback SMPS
- Zener diode replacement
- Voltage monitoring
- Precision constant current sink/source
- Comparator with integrated reference

3 Description

The ATL43xLI device is a three-terminal adjustable shunt regulator, with specified thermal stability over applicable automotive, commercial, and military temperature ranges. The output voltage can be set to any value between \( V_{\text{ref}} \) (approximately 2.5 V) and 36 V, with two external resistors. These devices have a typical output impedance of 0.3 Ω. Active output circuitry provides a very sharp turn-on characteristic, making these devices excellent replacements for Zener diodes in many applications, such as onboard regulation, adjustable power supplies, and switching power supplies. This device is a pin-to-pin alternative to the TL431LI and TL432LI, with lower minimum operating current to help reduce system power consumption. The ATL432LI device has exactly the same functionality and electrical specifications as the ATL431LI device, but has a different pinout for the DBZ package. The ATL431LI is also offered in a tiny X2SON (1.00 mm x 1.00 mm) package which makes it ideal for space constraint applications.

The ATL431LI device is offered in two grades, with initial tolerances (at 25°C) of 0.5%, and 1%, for the B and A grade, respectively. In addition, low output drift versus temperature ensures good stability over the entire temperature range.

The ATL43xLixQ devices are characterized for operation from \(-40^\circ\text{C}\) to \(+125^\circ\text{C}\).

### Device Information\(^{(1)}\)

<table>
<thead>
<tr>
<th>PART NUMBER</th>
<th>PACKAGE (PIN)</th>
<th>BODY SIZE (NOM)</th>
</tr>
</thead>
<tbody>
<tr>
<td>ATL43xLI</td>
<td>SOT-23 (3)</td>
<td>2.90 mm x 1.30 mm</td>
</tr>
<tr>
<td>ATL431LI</td>
<td>X2SON (4)</td>
<td>1.00 mm x 1.00 mm</td>
</tr>
</tbody>
</table>

\(^{(1)}\) For all available packages, see the orderable addendum at the end of the data sheet.

---

!! An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.
Table of Contents

1 Features .............................................................. 1
2 Applications ......................................................... 1
3 Description ............................................................. 1
4 Revision History ....................................................... 2
5 Device Comparison Table ........................................... 3
6 Pin Configuration and Functions ................................. 3
7 Specifications .......................................................... 4
   7.1 Absolute Maximum Ratings .................................. 4
   7.2 ESD Ratings ...................................................... 4
   7.3 Thermal Information ........................................... 4
   7.4 Recommended Operating Conditions ....................... 4
   7.5 Electrical Characteristics .................................... 5
8 Typical Characteristics ................................................ 6
9 Parameter Measurement Information ............................ 9
   9.1 Temperature Coefficient ..................................... 9
   9.2 Dynamic Impedance .......................................... 10
10 Detailed Description ................................................ 11
   10.1 Overview ....................................................... 11
   10.2 Functional Block Diagram .................................. 11
   10.3 Feature Description ........................................... 12

10.4 Device Functional Modes ..................................... 12
11 Applications and Implementation ............................... 13
   11.1 Application Information ..................................... 13
   11.2 Typical Applications ......................................... 13
   11.3 System Examples ............................................. 21
12 Power Supply Recommendations ................................ 25
13 Layout ................................................................. 25
   13.1 Layout Guidelines ............................................. 25
   13.2 SOT23-3 Layout Example .................................... 25
   13.3 X2SON (DQN) Layout Example ............................. 25
   13.4 Thermal Considerations ..................................... 26
14 Device and Documentation Support ............................... 27
   14.1 Documentation Support ..................................... 27
   14.2 Related Links .................................................. 27
   14.3 Receiving Notification of Documentation Updates ........... 27
   14.4 Community Resources ....................................... 27
   14.5 Trademarks .................................................... 27
   14.6 Electrostatic Discharge Caution ............................ 27
   14.7 Glossary ....................................................... 28
15 Mechanical, Packaging, and Orderable Information .......... 28

4 Revision History

Changes from Revision C (August 2019) to Revision D  Page
   • Changed typical graph to match Electrical Characteristics .................................................. 6
   • Added X2SON (DQN) Layout Example ................................................................. 25
   • Added Thermal Considerations .......................................................... 26

Changes from Revision B (November 2018) to Revision C  Page
   • Changed I_{min} description to match Electrical Characteristics ........................................... 1
   • Added X2SON package option ....................................................... 1
   • Added X2SON pinout and specifications .................................................. 3

Changes from Revision A (October 2018) to Revision B  Page
   • Changed ATL43xLI from Product Preview to Production Data ........................................... 1

Changes from Original (July 2018) to Revision A  Page
   • Initial release of full version ........................................... 1
   • Changed Stability Boundary Conditions for All ATL431, ATL432 Devices Above 1 mA graph ............ 7
   • Added Stability Boundary Conditions for All ATL431, ATL432 Devices Below 1 mA graph .............. 7
   • Added Test Circuit for Stability Boundary Conditions image ................................................ 7
5 Device Comparison Table

<table>
<thead>
<tr>
<th>DEVICE PINOUT</th>
<th>INITIAL ACCURACY</th>
<th>OPERATING FREE-AIR TEMPERATURE (T_A)</th>
</tr>
</thead>
<tbody>
<tr>
<td>ATL431LI</td>
<td>A: 1%</td>
<td>I: -40°C to 85°C</td>
</tr>
<tr>
<td>ATL432LI</td>
<td>B: 0.5%</td>
<td>Q: -40°C to 125°C</td>
</tr>
</tbody>
</table>

6 Pin Configuration and Functions

<table>
<thead>
<tr>
<th>Pin Functions</th>
</tr>
</thead>
<tbody>
<tr>
<td>NAME</td>
</tr>
<tr>
<td>Anode</td>
</tr>
<tr>
<td>Cathode</td>
</tr>
<tr>
<td>Ref</td>
</tr>
<tr>
<td>NC</td>
</tr>
<tr>
<td>Thermal Pad</td>
</tr>
</tbody>
</table>
7 Specifications

7.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)\(^{(1)}\)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>MIN</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>(V_{KA})</td>
<td></td>
<td>37</td>
<td>V</td>
</tr>
<tr>
<td>(I_{KA})</td>
<td>–10</td>
<td>18</td>
<td>mA</td>
</tr>
<tr>
<td>(I_{(ref)})</td>
<td>–5</td>
<td>10</td>
<td>mA</td>
</tr>
<tr>
<td>(T_J)</td>
<td>–40</td>
<td>150</td>
<td>C</td>
</tr>
<tr>
<td>(T_{stg})</td>
<td>–65</td>
<td>150</td>
<td>C</td>
</tr>
</tbody>
</table>

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under Recommended Operating Conditions. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values are with respect to ANODE, unless otherwise noted.

7.2 ESD Ratings

<table>
<thead>
<tr>
<th>Parameter</th>
<th>VALUE</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>(V_{(ESD)})</td>
<td>±2000</td>
<td>V</td>
</tr>
<tr>
<td>(V_{C101})</td>
<td>±1000</td>
<td>V</td>
</tr>
</tbody>
</table>

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

7.3 Thermal Information

<table>
<thead>
<tr>
<th>THERMAL METRIC(^{(1)})</th>
<th>ATL43xLI</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>DBZ</td>
</tr>
<tr>
<td></td>
<td>3 PINS</td>
</tr>
<tr>
<td>(R_{UA}) Junction-to-ambient thermal resistance</td>
<td>371.7</td>
</tr>
<tr>
<td>(R_{UC(top)}) Junction-to-case (top) thermal resistance</td>
<td>145.9</td>
</tr>
<tr>
<td>(R_{UB}) Junction-to-board thermal resistance</td>
<td>104.7</td>
</tr>
<tr>
<td>(\psi_{JT}) Junction-to-top characterization parameter</td>
<td>23.9</td>
</tr>
<tr>
<td>(\psi_{JB}) Junction-to-board characterization parameter</td>
<td>102.9</td>
</tr>
<tr>
<td>(R_{UC(bottom)}) Junction-to-case (bottom) thermal resistance</td>
<td>N/A</td>
</tr>
</tbody>
</table>

(1) For more information about traditional and new thermal metrics, see the Semiconductor and IC Package Thermal Metrics application report, SPR953.

7.4 Recommended Operating Conditions

See \(^{(1)}\)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>MIN</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>(V_{KA})</td>
<td></td>
<td>REF</td>
<td>V</td>
</tr>
<tr>
<td>(I_{KA})</td>
<td>0.08</td>
<td>15</td>
<td>mA</td>
</tr>
<tr>
<td>(T_A) Operating Free-Air Temperature</td>
<td>ATL43xLxI</td>
<td>–40</td>
<td>85</td>
</tr>
<tr>
<td></td>
<td>ATL43xLxQ</td>
<td>–40</td>
<td>125</td>
</tr>
</tbody>
</table>

(1) Maximum power dissipation is a function of \(T_{j(max)}\), \(\theta_{JA}\), and \(T_A\). The maximum allowable power dissipation at any allowable ambient temperature is \(P_D = (T_{j(max)} - T_A)/\theta_{JA}\). Operating at the absolute maximum \(T_J\) of 150°C can affect reliability.
7.5 Electrical Characteristics

over recommended operating conditions, $T_A = 25°C$ (unless otherwise noted)

<table>
<thead>
<tr>
<th>PARAMETER</th>
<th>TEST CIRCUIT</th>
<th>TEST CONDITIONS</th>
<th>MIN</th>
<th>TYP</th>
<th>MAX</th>
<th>UNIT</th>
</tr>
</thead>
<tbody>
<tr>
<td>$V_{REF}$</td>
<td>Reference Voltage</td>
<td>See Figure 17</td>
<td>$V_{KA} = V_{ref}, I_{KA} = 1 mA$</td>
<td>ATL43xLIAx devices</td>
<td>2475</td>
<td>2500</td>
</tr>
<tr>
<td>$V_{I(dev)}$</td>
<td>Deviation of reference input voltage over full temperature range $^{(1)}$</td>
<td>See Figure 17</td>
<td>$V_{KA} = V_{ref}, I_{KA} = 1 mA$</td>
<td>ATL43xLIXL devices</td>
<td>6</td>
<td>17</td>
</tr>
<tr>
<td>$\Delta V_{ref} / \Delta V_{KA}$</td>
<td>Ratio of change in reference voltage to the change in cathode voltage</td>
<td>See Figure 18</td>
<td>$I_{KA} = 1 mA$</td>
<td>$\Delta V_{KA} = 10 V - V_{ref}$</td>
<td>$-1.4$</td>
<td>$-2.7$</td>
</tr>
<tr>
<td>$I_{ref}$</td>
<td>Reference Input Current</td>
<td>See Figure 18</td>
<td>$I_{KA} = 1 mA, R1 = 10k\Omega, R2 = \infty$</td>
<td>0.2</td>
<td>0.4</td>
<td>µA</td>
</tr>
<tr>
<td>$I_{I(dev)}$</td>
<td>Deviation of reference input current over full temperature range $^{(1)}$</td>
<td>See Figure 18</td>
<td>$I_{KA} = 1 mA, R1 = 10k\Omega, R2 = \infty$</td>
<td>0.1</td>
<td>0.3</td>
<td>µA</td>
</tr>
<tr>
<td>$I_{min}$</td>
<td>Minimum cathode current for regulation</td>
<td>See Figure 17</td>
<td>$V_{KA} = V_{ref}$</td>
<td>65</td>
<td>80</td>
<td>µA</td>
</tr>
<tr>
<td>$I_{off}$</td>
<td>Off-state cathode current</td>
<td>See Figure 19</td>
<td>$V_{KA} = 36 V, V_{ref} = 0$</td>
<td>0.1</td>
<td>1</td>
<td>µA</td>
</tr>
<tr>
<td>$</td>
<td>Z_{KA}</td>
<td>$</td>
<td>Dynamic Impedance $^{(2)}$</td>
<td>See Figure 17</td>
<td>$V_{KA} = V_{ref}, I_{KA} = 1 mA$ to $15 mA$</td>
<td>0.3</td>
</tr>
</tbody>
</table>

$^{(1)}$ The deviation parameters $V_{I(dev)}$ and $I_{I(dev)}$ are defined as the differences between the maximum and minimum values obtained over the rated temperature range. For more details on $V_{I(dev)}$ and how it relates to the average temperature coefficient, see Parameter Measurement Information.

$^{(2)}$ The dynamic impedance is defined by $|Z_{KA}| = \Delta V_{KA}/\Delta I_{KA}$. For more details on $|Z_{KA}|$ and how it relates to $V_{KA}$, see Parameter Measurement Information.
8 Typical Characteristics

Data at high and low temperatures are applicable only within the recommended operating free-air temperature ranges of the various devices.
Figure 7. Small-Signal Voltage Amplification vs Frequency

Figure 8. Test Circuit for Voltage Amplification

Figure 9. Reference Impedance vs Frequency

Figure 10. Test Circuit for Reference Impedance

Figure 11. Pulse Response

Figure 12. Test Circuit for Pulse Response
Typical Characteristics (continued)

The areas under the curves represent conditions that may cause the device to oscillate. For curves B and C, R2 and V+ are adjusted to establish the initial $V_{KA}$ and $I_{KA}$ conditions, with $C_L = 0$. $V_{BATT}$ and $C_L$ are then adjusted to determine the ranges of stability.

**Figure 13. Stability Boundary Conditions for All ATL431LI, ATL432LI Devices Above 1 mA**

The areas in-between the curves represent conditions that may cause the device to oscillate. For curves B and C, R2 and V+ are adjusted to establish the initial $V_{KA}$ and $I_{KA}$ conditions, with $C_L = 0$. $V_{BATT}$ and $C_L$ are then adjusted to determine the ranges of stability.

**Figure 15. Stability Boundary Conditions for All ATL431LI, ATL432LI Devices Below 1 mA**

**Figure 14. Test Circuit for Stability Boundary Conditions**

**Figure 16. Test Circuit for Stability Boundary Conditions**
9 Parameter Measurement Information

Figure 17. Test Circuit for $V_{KA} = V_{ref}$

Figure 18. Test Circuit for $V_{KA} > V_{ref}$

Figure 19. Test Circuit for $I_{off}$

9.1 Temperature Coefficient

The deviation of the reference voltage, $V_{ref}$, over the full temperature range is known as $V_{I(dev)}$. The parameter of $V_{I(dev)}$ can be used to find the temperature coefficient of the device. The average full-range temperature coefficient of the reference input voltage, $\alpha_{Vref}$, is defined as:

$$\alpha_{Vref} \left( \frac{\text{ppm}}{^\circ C} \right) = \left( \frac{V_{I(dev)}}{V_{ref \text{ at } 25^\circ C}} \right) \times 10^6$$

where:

$\Delta T_A$ is the rated operating temperature range of the device.

$\alpha_{Vref}$ is positive or negative, depending on whether minimum $V_{ref}$ or maximum $V_{ref}$, respectively, occurs at the lower temperature. The full-range temperature coefficient is an average and therefore any subsection of the rated operating temperature range can yield a value that is greater or less than the average. For more details on temperature coefficient, check out Voltage Reference Selection Basics.
9.2 Dynamic Impedance

The dynamic impedance is defined as: 

\[ |Z_{KA}| = \frac{\Delta V_{KA}}{\Delta I_{KA}} \].

When the device is operating with two external resistors (see Figure 18), the total dynamic impedance of the circuit is given by: 

\[ |Z'| = \frac{\Delta V}{\Delta I} \approx |Z_{KA}| \left( 1 + \frac{R1}{R2} \right) \].

The \( V_{KA} \) of the ATL431LI can be affected by the dynamic impedance. The ATL431LI test current \( I_{test} \) for \( V_{KA} \) is specified on the Electrical Characteristics. Any deviation from \( I_{test} \) can cause deviation on the output \( V_{KA} \). Figure 20 shows the effect of the dynamic impedance on the \( V_{KA} \).

![Figure 20. Dynamic Impedance](image)
10 Detailed Description

10.1 Overview

This standard device has proven ubiquity and versatility across a wide range of applications, ranging from power to signal path. This is due to its key components containing an accurate voltage reference and opamp, which are very fundamental analog building blocks. ATL431LI is used in conjunction with its key components to behave as a single voltage reference, error amplifier, voltage clamp or comparator with integrated reference.

ATL431LI can be operated and adjusted to cathode voltages from 2.5V to 36V, making this part optimal for a wide range of end equipments in industrial, auto, telecom & computing. In order for this device to behave as a shunt regulator or error amplifier, >80µA (I_{min} (maximum)) must be supplied in to the cathode pin. Under this condition, feedback can be applied from the Cathode and Ref pins to create a replica of the internal reference voltage.

Various reference voltage options can be purchased with initial tolerances (at 25°C) of 0.5%, and 1%. These reference options are denoted by B (0.5%) and A (1.0%) after the ATL431LI or ATL432LI. ATL431LI and ATL432LI are both functionally the same, but have separate pinout options.

The ATL43xLIxQ devices are characterized for operation from –40°C to +125°C.

10.2 Functional Block Diagram

![Equivalent Schematic](Image)

**Figure 21. Equivalent Schematic**

![Detailed Schematic](Image)

**Figure 22. Detailed Schematic**
10.3 Feature Description

ATL431LI consists of an internal reference and amplifier that outputs a sink current based on the difference between the reference pin and the virtual internal pin. The sink current is produced by the internal Darlington pair, shown in the above schematic (Figure 21). A Darlington pair is used in order for this device to be able to sink a maximum current of 15 mA.

When operated with enough voltage headroom ($\geq 2.5$ V) and cathode current ($I_{KA}$), ATL431LI forces the reference pin to 2.5 V. However, the reference pin can not be left floating, as it needs $I_{REF} \geq 0.4$ $\mu$A (see Specifications). This is because the reference pin is driven into an NPN, which needs base current in order to operate properly.

When feedback is applied from the Cathode and Reference pins, ATL431LI behaves as a Zener diode, regulating to a constant voltage dependent on current being supplied into the cathode. This is due to the internal amplifier and reference entering the proper operating regions. The same amount of current needed in the above feedback situation must be applied to this device in open loop, servo or error amplifying implementations in order for it to be in the proper linear region giving ATL431LI enough gain.

Unlike many linear regulators, ATL431LI is internally compensated to be stable without an output capacitor between the cathode and anode. However, if it is desired to use an output capacitor Figure 13 can be used as a guide to assist in choosing the correct capacitor to maintain stability.

10.4 Device Functional Modes

10.4.1 Open Loop (Comparator)

When the cathode/output voltage or current of ATL431LI is not being fed back to the reference/input pin in any form, this device is operating in open loop. With proper cathode current ($I_{KA}$) applied to this device, ATL431LI will have the characteristics shown in SLVA987. With such high gain in this configuration, ATL431LI is typically used as a voltage comparator. The integrated voltage reference makes the ATL431LI a flexible device for monitoring a signal for undervoltage and overvoltage detection.

10.4.2 Closed Loop

When the cathode/output voltage or current of ATL431LI is being fed back to the reference/input pin in any form, this device is operating in closed loop. The majority of applications involving ATL431LI use it in this manner to regulate a fixed voltage or current. The feedback enables this device to behave as an error amplifier, computing a portion of the output voltage and adjusting it to maintain the desired regulation. This is done by relating the output voltage back to the reference pin in a manner to make it equal to the internal reference voltage, which can be accomplished via resistive or direct feedback.
11 Applications and Implementation

NOTE
Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI’s customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

11.1 Application Information
As this device has many applications and setups, there are many situations that this datasheet can not characterize in detail. The linked application notes will help the designer make the best choices when using this part.

Application note Understanding Stability Boundary Conditions Charts in TL431, TL432 Data Sheet, SLVA482 provides a deeper understanding of this device’s stability characteristics and aid the user in making the right choices when choosing a load capacitor. Application note Setting the Shunt Voltage on an Adjustable Shunt Regulator, SLVA445 assists with setting the shunt voltage to achieve optimum accuracy for this device.

11.2 Typical Applications

11.2.1 Comparator With Integrated Reference

![Comparator Application Schematic](image)

Figure 23. Comparator Application Schematic
Typical Applications (continued)

11.2.1.1 Design Requirements

For this design example, use the parameters listed in Table 1 as the input parameters.

<table>
<thead>
<tr>
<th>DESIGN PARAMETER</th>
<th>EXAMPLE VALUE</th>
</tr>
</thead>
<tbody>
<tr>
<td>Input Voltage Range</td>
<td>0 V to 5 V</td>
</tr>
<tr>
<td>Input Resistance</td>
<td>10 kΩ</td>
</tr>
<tr>
<td>Supply Voltage</td>
<td>24 V</td>
</tr>
<tr>
<td>Cathode Current (Ik)</td>
<td>5 mA</td>
</tr>
<tr>
<td>Output Voltage Level</td>
<td>~2 V – V$_{SUP}$</td>
</tr>
<tr>
<td>Logic Input Thresholds</td>
<td>V$_{L}$</td>
</tr>
</tbody>
</table>

Table 1. Design Parameters

11.2.1.2 Detailed Design Procedure

When using ATL431LI as a comparator with reference, determine the following:

- Input Voltage Range
- Reference Voltage Accuracy
- Output logic input high and low level thresholds
- Current Source resistance

11.2.1.2.1 Basic Operation

In the configuration shown in Figure 23 ATL431LI will behave as a comparator, comparing the V$_{REF}$ pin voltage to the internal virtual reference voltage. When provided a proper cathode current ($I_K$), ATL431LI will have enough open loop gain to provide a quick response. This can be seen in Figure 24, where the $R_{SUP}$=10 kΩ ($I_{KA}$=500 µA) situation responds much slower than $R_{SUP}$=1 kΩ ($I_{KA}$=5 mA). With the ATL431LI max Operating Current ($I_{MIN}$) being 0.08 mA, operation near that could result in low gain, leading to a slow response.

11.2.1.2.1.1 Overdrive

Slow or inaccurate responses can also occur when the reference pin is not provided enough overdrive voltage. This is the amount of voltage that is higher than the internal virtual reference. The internal virtual reference voltage will be within the range of 2.5 V ±(0.5% or 1.0%) depending on which version is being used. The more overdrive voltage provided, the faster the ATL431LI will respond.

For applications where ATL431LI is being used as a comparator, it is best to set the trip point to greater than the positive expected error (that is +1.0% for the A version). For fast response, setting the trip point to >10% of the internal V$_{REF}$ should suffice.

For minimal voltage drop or difference from Vin to the ref pin, TI recommends to use an input resistor <10kΩ to provide I$_{ref}$. 

11.2.1.2.2 Output Voltage and Logic Input Level

In order for ATL431LI to properly be used as a comparator, the logic output must be readable by the receiving logic device. This is accomplished by knowing the input high and low level threshold voltage levels, typically denoted by $V_{IH}$ and $V_{IL}$.

As seen in Figure 24, ATL431LI's output low level voltage in open-loop/comparator mode is approximately 2 V, which is typically sufficient for 5 V supplied logic. However, would not work for 3.3 V and 1.8 V supplied logic. To accommodate this a resistive divider can be tied to the output to attenuate the output voltage to a voltage legible to the receiving low voltage logic device.

ATL431's output high voltage is equal to $V_{SUP}$ due to ATL431LI being open-collector. If $V_{SUP}$ is much higher than the receiving logic's maximum input voltage tolerance, the output must be attenuated to accommodate the outgoing logic's reliability.

When using a resistive divider on the output, be sure to make the sum of the resistive divider (R1 and R2 in Figure 23) is much greater than $R_{SUP}$ in order to not interfere with ATL431LI's ability to pull close to $V_{SUP}$ when turning off.

11.2.1.2.2.1 Input Resistance

ATL431LI requires an input resistance in this application in order to source the reference current ($I_{REF}$) needed from this device to be in the proper operating regions while turning on. The actual voltage seen at the ref pin will be $V_{REF}=V_{IN}-I_{REF} \cdot R_{IN}$. Because $I_{REF}$ can be as high as 4 µA. TI recommends to use a resistance small enough that will mitigate the error that $I_{REF}$ creates from $V_{IN}$.

11.2.1.3 Application Curve

---

Figure 24. Output Response With Various Cathode Currents
11.2.2 Precision Constant Current Sink

**Figure 25. Precision Constant Current Sink Application Schematic**

### 11.2.2.1 Design Requirements

For this design example, use the parameters listed in Table 1 as the input parameters.

<table>
<thead>
<tr>
<th>DESIGN PARAMETER</th>
<th>EXAMPLE VALUE</th>
</tr>
</thead>
<tbody>
<tr>
<td>Supply Voltage (V_{I(BATT)})</td>
<td>5 V</td>
</tr>
<tr>
<td>Sink Current (I_{O})</td>
<td>100mA</td>
</tr>
<tr>
<td>Cathode Current (I_k)</td>
<td>5 mA</td>
</tr>
</tbody>
</table>

### 11.2.2.2 Detailed Design Procedure

When using ATL43xLI as a constant current sink, determine the following:

- Output Current Range
- Output Current Accuracy
- Power Consumption for ATL43xLI

#### 11.2.2.2.1 Basic Operation

In the configuration shown, ATL43xLI acts as a control component within a feedback loop of the constant current sink. Working with an external passing component such as an BJT, ATL43xLI provides precision current sink with accuracy set by itself and the sense resistor R_S. This circuit can also be used as LED driving circuit.

#### 11.2.2.2.1.1 Output Current Range and Accuracy

The output current range of the circuit is determined by the equation shown in the configuration. Keep in mind that the V_{REF} equals to 2.5V. When choosing the sense resistor R_S, it needs to generate 2.5V for the ATL43xLI when I_O reaches the target current. If the overhead voltage of 2.5V is not acceptable, please consider lower voltage reference devices such as TLV43x or TLVH43x.

The output current accuracy is determined by both the accuracy of ATL43xLI chosen, as well as the accuracy of the sense resistor R_S. The internal virtual reference voltage of ATL43xLI will be within the range of 2.5 V ±(0.5% or 1.0%) depending on which version is being used. Another consideration for the output current accuracy is the temperature coefficient of the ATL43xLI and R_S. Please refer to the electrical characterization table for the specification of these parameters.

#### 11.2.2.2.2 Power Consumption

In order for ATL43xLI to properly be used as a control component in this circuit, the minimum operating current needs to be reached. This is accomplished by setting the external biasing resistor in series with the ATL43xLI.

For ATL43xLI, the minimum operating current is 80µA and with margin consideration, most of the designs set this current to be higher than 100µA. To achieve lower power consumption, please consider devices such as ATL43x.
11.2.3 Shunt Regulator/Reference

![Shunt Regulator Schematic](image)

**Figure 26. Shunt Regulator Schematic**

### 11.2.3.1 Design Requirements

For this design example, use the parameters listed in Table 1 as the input parameters.

<table>
<thead>
<tr>
<th>DESIGN PARAMETER</th>
<th>EXAMPLE VALUE</th>
</tr>
</thead>
<tbody>
<tr>
<td>Reference Initial Accuracy</td>
<td>1.0%</td>
</tr>
<tr>
<td>Supply Voltage</td>
<td>24 V</td>
</tr>
<tr>
<td>Cathode Current (Ik)</td>
<td>5 mA</td>
</tr>
<tr>
<td>Output Voltage Level</td>
<td>2.5 V - 36 V</td>
</tr>
<tr>
<td>Load Capacitance</td>
<td>2 µF</td>
</tr>
<tr>
<td>Feedback Resistor Values and Accuracy (R1 and R2)</td>
<td>10 kΩ</td>
</tr>
</tbody>
</table>

### 11.2.3.2 Detailed Design Procedure

When using ATL431LI as a Shunt Regulator, determine the following:

- Input Voltage Range
- Temperature Range
- Total Accuracy
- Cathode Current
- Reference Initial Accuracy
- Output Capacitance

#### 11.2.3.2.1 Programming Output/Cathode Voltage

In order to program the cathode voltage to a regulated voltage a resistive bridge must be shunted between the cathode and anode pins with the mid point tied to the reference pin. This can be seen in Figure 26, with R1 and R2 being the resistive bridge. The cathode/output voltage in the shunt regulator configuration can be approximated by the equation shown in Figure 26. The cathode voltage can be more accurately determined by taking into account the cathode current:

\[ V_o = \left(1 + \frac{R_1}{R_2}\right) V_{ref} - I_{ref} \times R_1 \]

In order for this equation to be valid, ATL431LI must be fully biased so that it has enough open loop gain to mitigate any gain error. This can be done by meeting the Imin spec denoted in Specifications.
11.2.3.2.2 Total Accuracy

When programming the output above unity gain ($V_{KA}=V_{REF}$), ATL431LI is susceptible to other errors that may effect the overall accuracy beyond $V_{REF}$. These errors include:

- R1 and R2 accuracies
- $V_{I(dev)}$ - Change in reference voltage over temperature
- $\Delta V_{REF} / \Delta V_{KA}$ - Change in reference voltage to the change in cathode voltage
- $|z_{KA}|$ - Dynamic impedance, causing a change in cathode voltage with cathode current

Worst case cathode voltage can be determined taking all of the variables into account. Application note Setting the Shunt Voltage on an Adjustable Shunt Regulator, SLVA445 assists designers in setting the shunt voltage to achieve optimum accuracy for this device.

11.2.3.2.3 Stability

Though ATL431LI is stable with no capacitive load, the device that receives the shunt regulator’s output voltage could present a capacitive load that is within the ATL431LI region of stability, shown in Figure 13. Also, designers may use capacitive loads to improve the transient response or for power supply decoupling. When using additional capacitance between Cathode and Anode, see Figure 13. Also, application note Understanding Stability Boundary Conditions Charts in TL431, TL432 Data Sheet, SLVA482 will provide a deeper understanding of this device’s stability characteristics and aid the user in making the right choices when choosing a load capacitor.

11.2.3.2.4 Start-Up Time

As shown in Figure 27, ATL431LI has a fast response up to approximately 2 V and then slowly charges to its programmed value. This is due to the compensation capacitance (shown in Figure 13) the ATL43xLIx has to meet its stability criteria. Despite the secondary delay, ATL43xLIx still has a fast response suitable for many clamp applications.

11.2.3.3 Application Curve

Figure 27. ATL43xLIx Start-Up Response
11.2.4 Isolated Flyback with Optocoupler

![Diagram of Isolated Flyback with Optocoupler](image)

**Figure 28. Isolated Flyback with Optocoupler**

11.2.4.1 Design Requirements

The ATL431LI is used in the feedback network on the secondary side for an isolated flyback with optocoupler design. Figure 28 shows the simplified flyback converter that used the ATL431LI. For this design example, use the parameters in Table 4 as the input parameters.

**Table 4. Design Parameters**

<table>
<thead>
<tr>
<th>DESIGN PARAMETER</th>
<th>EXAMPLE VALUE</th>
</tr>
</thead>
<tbody>
<tr>
<td>Voltage Output</td>
<td>20 V</td>
</tr>
<tr>
<td>Feedback Network Quiescent Current (I_q)</td>
<td>&lt;40 mW</td>
</tr>
</tbody>
</table>

11.2.4.1.1 Detailed Design Procedure

In this example, a simplified design procedure will be discussed. The compensation network for the feedback network is beyond the scope of this section. Details on compensation network can be found on SLUA671.

The goal of this design is to design a low standby current feedback network to meet the Europe CoC Tier 2 and United States DoE Level VI requirements. To meet the design requirements, the system standby power needs to be below 75mW. In order to meet this, the feedback network needs to consume less than 40mW to allow margin for the power losses on the primary side controller and passive components and this can pose a challenge in systems greater than 10V.
11.2.4.1.1.1 ATL431LI Biasing

Figure 29 shows the simplified version of the feedback network. The standby $I_q$ of the system is dependent on two paths, ATL431LI biasing path and the resistor feedback path. With the given design requirements the total current through the feedback network cannot exceed 2mA.

The design goal is to take full advantage of the $I_{min}$ to set the $I_{KA}$ of the ATL431LI. The benefit of the ATL431LI is its low $I_{min}$ of 80 µA which allows the $I_{KA}$ to be lower at a full load condition compared to typical TL431LI devices. This helps lower the $I_{KA}$ at the no-load condition which is higher than the full load condition due to the dynamic changes in the $I_{KA}$ as the system load varies. The $I_{KA}$ at no-load, $I_{OPTNL}$, is dependent the value of $R_s$ which is the biasing resistor. $R_s$ is very application specific and is dependent on variables such as optocoupler's CTR, voltage, and current at no-load and this can be seen on Equation 2. By using an optocoupler with a high CTR it is possible to lower $I_{OPTNL}$ to a value of 1.5 mA for a power loss of 30 mW.

$$R_s \approx (V_{OUT} - V_{OPTNL} - 2) / I_{OPTNL}$$

$V_{OPTNL}$ = Optocoupler Voltage at No–Load Conditions

$I_{OPTNL}$ = Optocoupler Current at No–Load Conditions

(2)

11.2.4.1.1.2 Resistor Feedback Network

The feedback resistors set the output voltage of the secondary side and will consume the same $I_q$ at a fixed voltage. The design goal for the feedback resistor path is to minimize the resistor error while maintaining a low $I_q$. For this system example the feedback network path in this design will consume 0.5 mA to allow enough current for ATL431LI biasing. The resistors, $R_1$ and $R_2$, are sized based on a 0.5 mA budget for $I_q$ and $I_{REF}$. By using the resistor values from Equation 3 and Equation 4 the total power consumption will be 10mW and this can be further decreased by using larger resistors.

$$R_1 = (V_{OUT} - V_{REF}) / I_{FB}$$

$$R_1 = (20 V - 2.5 V) / 0.5 mA$$

$R_1 = 35k\Omega$

$$R_2 = V_{REF} / (I_{FB} - I_{REF})$$

$$R_2 = 2.5 V / (0.5 mA - 0.4 \mu A)$$

$R_2 = 5.004 k\Omega$

(3)

(4)
11.3 System Examples

A. R should provide cathode current ≥ 0.08 mA to the ATL431LI at minimum \( V_{\text{BATT}} \).

**Figure 30.** Precision High-Current Series Regulator

**Figure 31.** Output Control of a Three-Terminal Fixed Regulator

**Figure 32.** High-Current Shunt Regulator
System Examples (continued)

A. Refer to the stability boundary conditions in and Figure 13 to determine allowable values for C.

**Figure 33. Crowbar Circuit**

A. $R_b$ should provide cathode current ≥0.08 mA to the ATL431LI.

**Figure 35. Efficient 5-V Precision Regulator**
System Examples (continued)

![Figure 36. PWM Converter With Reference](image)

**Figure 36. PWM Converter With Reference**

A. Select R3 and R4 to provide the desired LED intensity and cathode current $\geq 0.08$ mA to the ATL431LI at the available $V_{I(BATT)}$.

![Figure 37. Voltage Monitor](image)

**Figure 37. Voltage Monitor**

Low Limit = \(1 + \frac{R_{1B}}{R_{2B}}\)\(V_{ref}\)

High Limit = \(1 + \frac{R_{1A}}{R_{2A}}\)\(V_{ref}\)

LED on When Low Limit < $V_{I(BATT)}$ < High Limit

![Figure 38. Delay Timer](image)

**Figure 38. Delay Timer**

\[\text{Delay} = R \times C \times \ln\left(\frac{12\ V}{12\ V - V_{ref}}\right)\]
System Examples (continued)

**Figure 39. Precision Current Limiter**

\[ I_{out} = \frac{V_{\text{ref}}}{R_{CL}} + I_{KA} \]

\[ R_1 = \frac{V_{I(BATT)}}{\frac{I_O}{h_{FE}} + I_{KA}} \]

**Figure 40. Precision Constant-Current Sink**

\[ I_O = \frac{V_{\text{ref}}}{R_S} \]
12 Power Supply Recommendations

When using ATL43xLIx as a Linear Regulator to supply a load, designers will typically use a bypass capacitor on the output/cathode pin. When doing this, be sure that the capacitance is within the stability criteria shown in Figure 13.

To not exceed the maximum cathode current, be sure that the supply voltage is current limited. Also, be sure to limit the current being driven into the Ref pin, as not to exceed its absolute maximum rating.

For applications shunting high currents, pay attention to the cathode and anode trace lengths, adjusting the width of the traces to have the proper current density.

13 Layout

13.1 Layout Guidelines

Bypass capacitors should be placed as close to the part as possible. Current-carrying traces need to have widths appropriate for the amount of current they are carrying; in the case of the ATL43xLIx, these currents will be low.

13.2 SOT23-3 Layout Example

![Figure 41. DBZ Layout Example](image1)

13.3 X2SON (DQN) Layout Example

![Figure 42. DQN Layout Example](image2)
13.4 Thermal Considerations

The thermal performance of the ATL431LI will depend on the power dissipation, thermal resistance, and ambient temperature. The ability to remove heat from the die is different for each package type, presenting different considerations in the printed-circuit-board (PCB) layout. The PCB area around the device that is free of other components moves the heat from the device to the ambient air. Performance data for JEDEC thermal metrics are given in the Specifications table.

Power dissipation depends on input voltage and load conditions. Power dissipation (\(P_D\)) is equal to the product of the output current and the voltage drop across the output pass element. For a ATL431LI, the pass element voltage drop will be across the cathode and anode as shown in Equation 5. In certain packages, like the DQN package, the thermal metrics will vary with how the thermal pad is connected. The DQN package is designed to be soldered to a thermal pad on the board. It is recommended that the DQN thermal pad is connected to a thermal dissipative section of the PCB if the ATL431LI in DQN package is expected to dissipate a significant amount of power. It is recommended to use large biasing resistors to keep the cathode current low on the ATL431LI for better thermal performance. For more information on designing and manufacturing with DQN, see Texas Instruments literature number SLUA271 and SCEA055. For reliable operation, limit junction temperature to 125°C (maximum) or its respective temperature maximum from the Recommended Operating Conditions.

\[
P_D = (V_{KA} - V_{ANODE}) / I_{KA}
\]  

(5)
14 Device and Documentation Support

14.1 Documentation Support

14.1.1 Device Nomenclature

TI assigns suffixes and prefixes to differentiate all the combinations of the ATL43xLI family. More details and possible orderable combinations are located in the Package Option Addendum.

<table>
<thead>
<tr>
<th>Product</th>
<th>Initial Accuracy</th>
<th>Operating Free-Air Temperature</th>
<th>Package Type</th>
<th>Package Quantity</th>
</tr>
</thead>
<tbody>
<tr>
<td>1: ATL431LI 2: ATL432LI*</td>
<td>B: 0.5% A: 1%</td>
<td>I: -40°C to 85°C Q: -40°C to 125°C</td>
<td>DBZ: SOT-23-3 DQN: X2SON</td>
<td>R: Tape &amp; Reel</td>
</tr>
</tbody>
</table>

*(Cathode and REF pins are switched)

14.1.2 Related Documentation

For related documentation see the following:

- Understanding Stability Boundary Conditions Charts in TL431, TL432 Data Sheet, SLVA482
- Setting the Shunt Voltage on an Adjustable Shunt Regulator, SLVA445

14.2 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to order now.

<table>
<thead>
<tr>
<th>PARTS</th>
<th>PRODUCT FOLDER</th>
<th>ORDER NOW</th>
<th>TECHNICAL DOCUMENTS</th>
<th>TOOLS &amp; SOFTWARE</th>
<th>SUPPORT &amp; COMMUNITY</th>
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</thead>
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<tr>
<td>ATL431LI</td>
<td>Click here</td>
<td>Click here</td>
<td>Click here</td>
<td>Click here</td>
<td>Click here</td>
</tr>
<tr>
<td>ATL432LI</td>
<td>Click here</td>
<td>Click here</td>
<td>Click here</td>
<td>Click here</td>
<td>Click here</td>
</tr>
</tbody>
</table>

14.3 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on Alert me to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

14.4 Community Resources

TI E2E™ support forums are an engineer's go-to source for fast, verified answers and design help — straight from the experts. Search existing answers or ask your own question to get the quick design help you need.

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14.5 Trademarks

E2E is a trademark of Texas Instruments.

All other trademarks are the property of their respective owners.

14.6 Electrostatic Discharge Caution

This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.
14.7 Glossary

SLYZ022 — *Ti Glossary.*

This glossary lists and explains terms, acronyms, and definitions.

15 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.
### PACKAGING INFORMATION

<table>
<thead>
<tr>
<th>Orderable Device</th>
<th>Status</th>
<th>Package Type</th>
<th>Package Drawing</th>
<th>Pins</th>
<th>Package Qty</th>
<th>Eco Plan</th>
<th>Lead/Ball Finish</th>
<th>MSL Peak Temp</th>
<th>Op Temp (°C)</th>
<th>Device Marking</th>
<th>Samples</th>
</tr>
</thead>
<tbody>
<tr>
<td>ATL431LIAIDBZR</td>
<td>ACTIVE</td>
<td>SOT-23</td>
<td>DBZ</td>
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<td>3000</td>
<td>Green (RoHS &amp; no Sb/Br)</td>
<td>NIPDAU</td>
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<td>1TUP</td>
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<td>1TVP</td>
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<td>1BKP</td>
<td>Samples</td>
</tr>
</tbody>
</table>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBsolete:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF ATL431LI, ATL432LI:

- Automotive: ATL431LI-Q1, ATL432LI-Q1

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
### TAPE AND REEL INFORMATION

**DEVICE**

- **Device**: ATL431LIAIDBZR
  - Package Type: SOT-23
  - Package Drawing: DBZ
  - Pins: 3
  - SPQ: 3000
  - Reel Diameter (mm): 178.0
  - Reel Width (W1) (mm): 9.2
  - A0 (mm): 3.15
  - B0 (mm): 2.77
  - K0 (mm): 1.22
  - P1 (mm): 4.0
  - W (mm): 8.0
  - Pin 1 Quadrant: Q3

- **Device**: ATL431LIAIDBZR
  - Package Type: SOT-23
  - Package Drawing: DBZ
  - Pins: 3
  - SPQ: 3000
  - Reel Diameter (mm): 178.0
  - Reel Width (W1) (mm): 9.0
  - A0 (mm): 3.15
  - B0 (mm): 2.77
  - K0 (mm): 1.22
  - P1 (mm): 4.0
  - W (mm): 8.0
  - Pin 1 Quadrant: Q3

- **Device**: ATL431LIAIDQNR
  - Package Type: X2SON
  - Package Drawing: DQN
  - Pins: 4
  - SPQ: 3000
  - Reel Diameter (mm): 180.0
  - Reel Width (W1) (mm): 9.5
  - A0 (mm): 1.16
  - B0 (mm): 1.16
  - K0 (mm): 0.5
  - P1 (mm): 4.0
  - W (mm): 8.0
  - Pin 1 Quadrant: Q2

- **Device**: ATL431LIBIDBZR
  - Package Type: SOT-23
  - Package Drawing: DBZ
  - Pins: 3
  - SPQ: 3000
  - Reel Diameter (mm): 178.0
  - Reel Width (W1) (mm): 9.2
  - A0 (mm): 3.15
  - B0 (mm): 2.77
  - K0 (mm): 1.22
  - P1 (mm): 4.0
  - W (mm): 8.0
  - Pin 1 Quadrant: Q3

- **Device**: ATL431LIBIDBZR
  - Package Type: SOT-23
  - Package Drawing: DBZ
  - Pins: 3
  - SPQ: 3000
  - Reel Diameter (mm): 178.0
  - Reel Width (W1) (mm): 9.0
  - A0 (mm): 3.15
  - B0 (mm): 2.77
  - K0 (mm): 1.22
  - P1 (mm): 4.0
  - W (mm): 8.0
  - Pin 1 Quadrant: Q3

- **Device**: ATL431LIAQDBZR
  - Package Type: SOT-23
  - Package Drawing: DBZ
  - Pins: 3
  - SPQ: 3000
  - Reel Diameter (mm): 178.0
  - Reel Width (W1) (mm): 9.0
  - A0 (mm): 3.15
  - B0 (mm): 2.77
  - K0 (mm): 1.22
  - P1 (mm): 4.0
  - W (mm): 8.0
  - Pin 1 Quadrant: Q3

- **Device**: ATL431LIAQDBZR
  - Package Type: X2SON
  - Package Drawing: DQN
  - Pins: 4
  - SPQ: 3000
  - Reel Diameter (mm): 180.0
  - Reel Width (W1) (mm): 9.5
  - A0 (mm): 1.16
  - B0 (mm): 1.16
  - K0 (mm): 0.5
  - P1 (mm): 4.0
  - W (mm): 8.0
  - Pin 1 Quadrant: Q2

- **Device**: ATL431LIBQDBZR
  - Package Type: SOT-23
  - Package Drawing: DBZ
  - Pins: 3
  - SPQ: 3000
  - Reel Diameter (mm): 178.0
  - Reel Width (W1) (mm): 9.0
  - A0 (mm): 3.15
  - B0 (mm): 2.77
  - K0 (mm): 1.22
  - P1 (mm): 4.0
  - W (mm): 8.0
  - Pin 1 Quadrant: Q3

- **Device**: ATL431LIBQDBZR
  - Package Type: X2SON
  - Package Drawing: DQN
  - Pins: 4
  - SPQ: 3000
  - Reel Diameter (mm): 180.0
  - Reel Width (W1) (mm): 9.5
  - A0 (mm): 1.16
  - B0 (mm): 1.16
  - K0 (mm): 0.5
  - P1 (mm): 4.0
  - W (mm): 8.0
  - Pin 1 Quadrant: Q2

- **Device**: ATL432LIAIDBZR
  - Package Type: SOT-23
  - Package Drawing: DBZ
  - Pins: 3
  - SPQ: 3000
  - Reel Diameter (mm): 178.0
  - Reel Width (W1) (mm): 9.2
  - A0 (mm): 3.15
  - B0 (mm): 2.77
  - K0 (mm): 1.22
  - P1 (mm): 4.0
  - W (mm): 8.0
  - Pin 1 Quadrant: Q3

- **Device**: ATL432LIAIDBZR
  - Package Type: SOT-23
  - Package Drawing: DBZ
  - Pins: 3
  - SPQ: 3000
  - Reel Diameter (mm): 178.0
  - Reel Width (W1) (mm): 9.0
  - A0 (mm): 3.15
  - B0 (mm): 2.77
  - K0 (mm): 1.22
  - P1 (mm): 4.0
  - W (mm): 8.0
  - Pin 1 Quadrant: Q3

- **Device**: ATL432LIAQDBZR
  - Package Type: SOT-23
  - Package Drawing: DBZ
  - Pins: 3
  - SPQ: 3000
  - Reel Diameter (mm): 178.0
  - Reel Width (W1) (mm): 9.0
  - A0 (mm): 3.15
  - B0 (mm): 2.77
  - K0 (mm): 1.22
  - P1 (mm): 4.0
  - W (mm): 8.0
  - Pin 1 Quadrant: Q3

- **Device**: ATL432LIAQDBZR
  - Package Type: X2SON
  - Package Drawing: DQN
  - Pins: 4
  - SPQ: 3000
  - Reel Diameter (mm): 180.0
  - Reel Width (W1) (mm): 9.5
  - A0 (mm): 1.16
  - B0 (mm): 1.16
  - K0 (mm): 0.5
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  - Pin 1 Quadrant: Q2

- **Device**: ATL432LIBIDBZR
  - Package Type: SOT-23
  - Package Drawing: DBZ
  - Pins: 3
  - SPQ: 3000
  - Reel Diameter (mm): 178.0
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  - Pin 1 Quadrant: Q3

- **Device**: ATL432LIBIDBZR
  - Package Type: SOT-23
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*All dimensions are nominal.*
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Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Reference JEDEC registration TO-236, except minimum foot length.
NOTES: (continued)

4. Publication IPC-7351 may have alternate designs.
5. Solder mask tolerances between and around signal pads can vary based on board fabrication site.
NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

7. Board assembly site may have different recommendations for stencil design.
Images above are just a representation of the package family, actual package may vary. Refer to the product data sheet for package details.
NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for optimal thermal and mechanical performance.
4. Features may not exist. Recommend use of pin 1 marking on top of package for orientation purposes.
5. Shape of exposed side leads may differ.
6. Number and location of exposed tie bars may vary.
NOTES: (continued)

7. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

8. If any vias are implemented, it is recommended that vias under paste be filled, plugged or tented.
9. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
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